

ABSTRACT OF THE DISCLOSURE

Disclosed is a technique capable of suppressing the damage of a semiconductor manufacturing apparatus due to the breakage or the crack to the minimum by surely detecting the breakage or the crack on a part of a wafer in a semiconductor manufacturing apparatus of a multi-chamber system. An entire image of a wafer is photographed by a camera in each time when the wafer is processed, and the photographed image is processed by a discrimination unit, thereby determining the presence of the breakage or the crack on the wafer. When the breakage or the crack is detected, an error signal is transmitted from the discrimination unit to a computer that controls the semiconductor manufacturing apparatus, and the operations of the process chamber and the transport chamber used immediately before the detection of the breakage or the crack on the wafer are stopped.

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